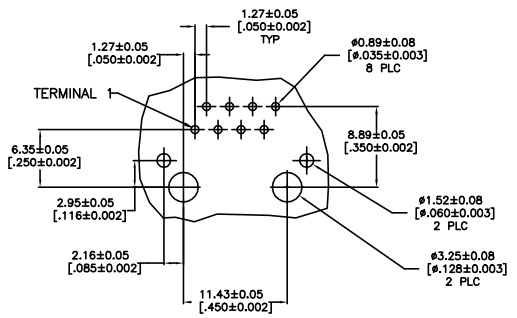
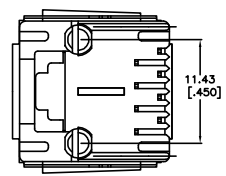
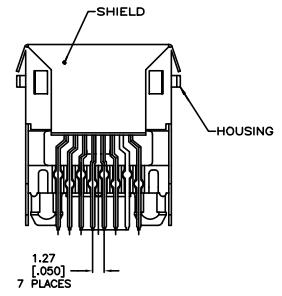
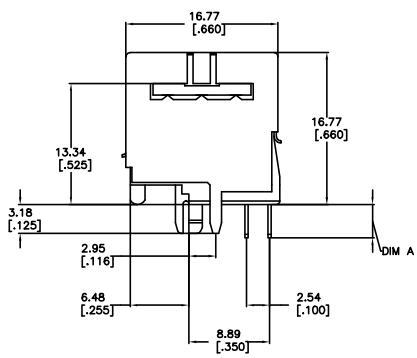
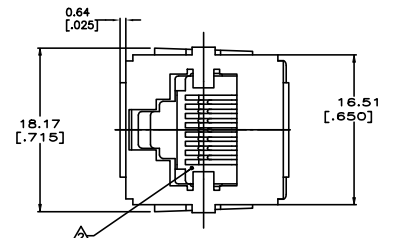
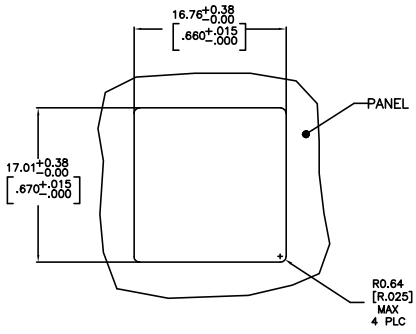


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REVISIONS			
REV	DATE	DESCRIPTION	BY
E1	05SEP2019	ECO-19-013839	IT SH



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

- 1 MATERIAL:
HOUSING - POLYESTER MOLDING COMPOUND, COLOR: BLACK
TERMINALS - 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD - COPPER ZINC ALLOY PLATED WITH 3.0µm [.000120] MIN THICK REFLOWED TIN.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 3 MATERIAL:
HOUSING - HIGH TEMP THERMOPLASTIC-LCP, COLOR: BLACK
TERMINALS - 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD - COPPER ZINC ALLOY PLATED WITH 3.0µm [.000120] MIN THICK REFLOWED TIN.
- 4 RECOMMENDED DIAMETER OF POSITION HOLE ON PCB FOR 5557969-3, 5557969-4 IS 3.175±0.08MM
- 5 SAME AS 5557969-3 BUT RESTRICTED TO CUSTOMNER

MATERIAL	DIM A	PART NUMBER
1	2.79-3.56 [1.25±.015]	5557969-4
4	2.79-3.56 [1.25±.015]	5557969-3
1	2.79-3.30 [1.20±.010]	5557969-2
1	2.79-3.56 [1.25±.015]	5557969-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONS: (mm) (INCHES). MATERIAL: SEE NOTE 1. CUSTOMER DRAWING.

DESIGNER: A. FERNANDEZ-RODRIGUEZ. CHECKER: J. WESTMAN. DATE: 108-1163. APPLICATION SPEC: 114-2048. REV: 0.000000. SCALE: 4:1. SHEET: 1 OF 1. REV: E1.

TE Connectivity
 S. FLICKINGER
 108-1163
 114-2048
 0.000000
 A100779
 C=5557969